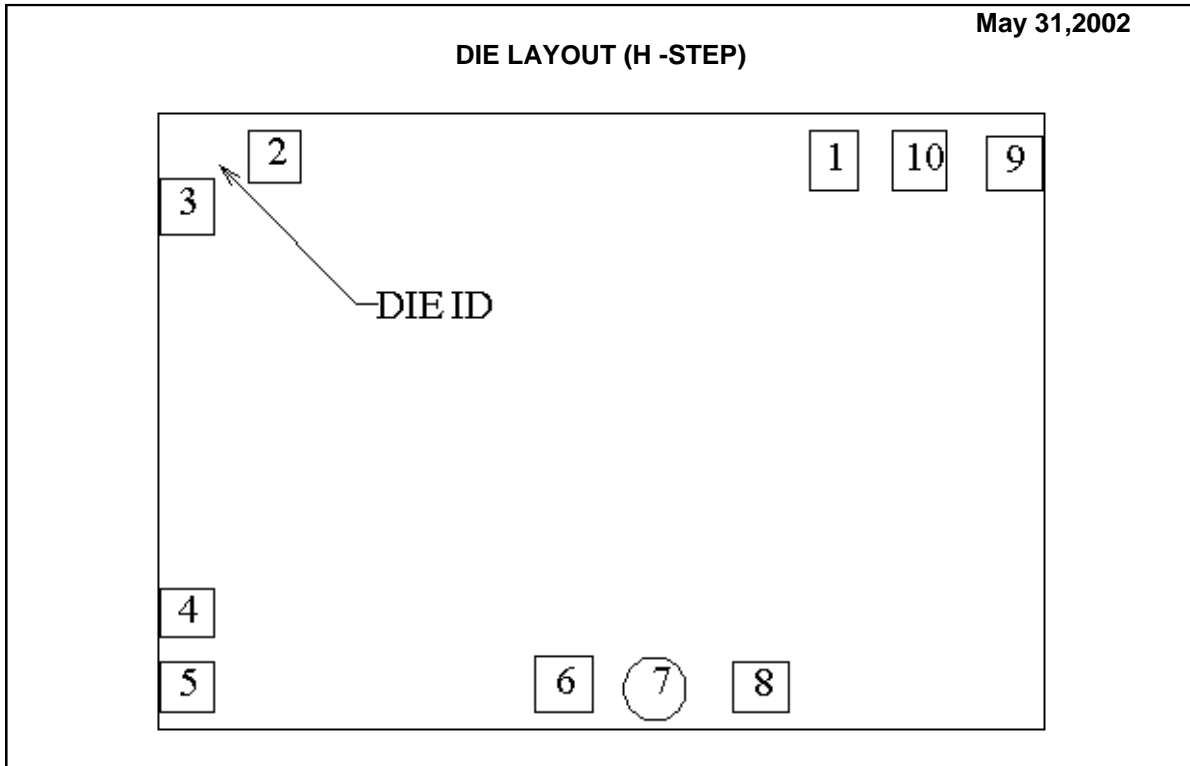


**LM111 MD8 MCD1390A**  
**VOLTAGE COMPARATOR**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	111H	Bond Pad Opening Size (min)	91 $\mu$ m x 112 $\mu$ m
Die Step	H	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1651 $\mu$ m x 1143 $\mu$ m 65mils x 45mils	Back Side Connection	Floating
Thickness	330 $\mu$ m Nominal		
Min Pitch	140 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (H -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
GND	1	434	485	91	x	112
INPUT+	2	-607	493	97	x	97
INPUT-	3	-771	400	99	x	104
V-	4	-771	-356	99	x	91
Balance	5	-771	-495	99	x	91
Balance/Strobe	6	-69	-489	107	x	104
NC	7	114	-483	117	x	117
NC	8	298	-495	104	x	91
Output	9	768	479	104	x	99
V+	10	593	485	99	x	112

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